F. No. 28(8)/2013-IPHW GOVERNMENT OF INDIA

MINISTRY OF COMMUNICATIONS & INFORMATION TECHNOLOGY DEPARTMENT OF ELECTRONICS & INFORMATION TECHNOLOGY ELECTRONICS NIKETAN, 6, CGO COMPLEX, LODHI ROAD, NEW DELHI –110003

December 12, 2014

DeitY invites proposals (Technical & Financial) from eligible bidders which are valid for a minimum period of 90 days from the date of submission on behalf of the President of India for 3rd party appraisal of Detailed Project Reports received by Government of India for setting up Semiconductor Wafer Fabrication manufacturing facilities in India.

Non-Refundable Document Fee	Rs. 5000/- (Rupees five thousand only)
Earnest Money Deposit to be submitted	Rs. 2,00,000/- (Rupees two lakh only)
Last day of submission of pre-bid queries	19.12.2014 (by 3:00 P.M. IST)
Date and time of pre-bid meeting	22.12.2014 (04:00 P.M. IST)
Issue of corrigendum/ clarifications	29.12.2014
Last date and time of proposal submission	27.01.2015 (03:00 P.M. IST)

Prospective bidders desirous of participating in this RFP may submit their queries to the undersigned as per the timelines mentioned above. Based on queries received, if required, DeitY may issue corrigendum/clarifications.

Interested parties may view and download the RFP document containing the detailed terms & conditions, evaluation criteria, and scope of work from the website http://eprocure.gov.in/eprocure/app or http://eprocure.gov.in/eprocure/app

S.K. Marwaha Scientist 'F'

Phone: 24365940

Email: smarwah@deity.gov.in